

Title (en)

HIGH-ENTROPY ALLOY AND METHOD FOR MANUFACTURING SAME

Title (de)

LEGIERUNG MIT HOHER ENTROPIE UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)

ALLIAGE À ENTROPIE ÉLEVÉE ET PROCÉDÉ DE FABRICATION D'UN TEL ALLIAGE

Publication

**EP 4151766 A4 20231220 (EN)**

Application

**EP 20934927 A 20200512**

Priority

KR 2020006209 W 20200512

Abstract (en)

[origin: EP4151766A1] A high-entropy alloy according to the present embodiment is a high-entropy alloy having an iron-rich phase and a copper-rich phase, and comprises a common complete solid solution metal that is completely solid-solved in iron and copper respectively. For example, the common complete solid solution metal may comprise nickel.

IPC 8 full level

**C22C 30/02** (2006.01); **C22C 38/02** (2006.01); **C22C 38/04** (2006.01); **C22C 38/06** (2006.01); **C22C 38/42** (2006.01); **C22C 38/58** (2006.01)

CPC (source: EP US)

**C22C 1/02** (2013.01 - US); **C22C 30/02** (2013.01 - EP US); **C22C 33/04** (2013.01 - US); **C22C 38/02** (2013.01 - EP); **C22C 38/04** (2013.01 - EP); **C22C 38/06** (2013.01 - EP US); **C22C 38/42** (2013.01 - EP US); **C22C 38/58** (2013.01 - EP US)

Citation (search report)

- [XII] DE 2031723 A1 19710107
- [XAI] KR 20200006906 A 20200121 - LG ELECTRONICS INC [KR], et al
- [XAI] US 2017275745 A1 20170928 - HONG SUN IG [KR], et al
- [A] CN 109252083 A 20190122 - ANYANG INST TECH, et al
- See references of WO 2021230392A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 4151766 A1 20230322**; **EP 4151766 A4 20231220**; US 2023183846 A1 20230615; WO 2021230392 A1 20211118

DOCDB simple family (application)

**EP 20934927 A 20200512**; KR 2020006209 W 20200512; US 202017924450 A 20200512